



# Product Change Notification

## 108536 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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# Product Change Notification

**Change Notification #:** 108536 - 00  
**Change Title:** Intel® Carrier Grade Server TIGH2U, PCN 108536-00, Product Design, Move wall of air duct away from PCI keep-out zone  
**Date of Publication:** June 09, 2008

## Key Characteristics of the Change:

Product Design

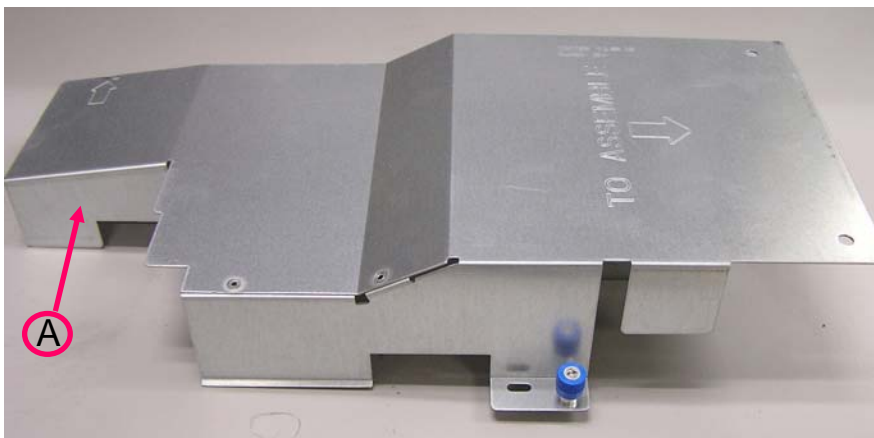
## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Sep 12, 2008
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*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

Intel moved the wall of the CPU/DIMM air duct 1.75mm toward DIMM slot#1 to resolve the interference issue with low-profile PCI boards. The wall location was changed by modifying the "break" in the sheet metal. See label "A" in the photo that follows.



## Customer Impact of Change and Recommended Action:

Intel anticipates no customer impact based on this change.

**Products Affected / Intel Ordering Codes:**

<b>Pre Change Product Code</b>	<b>Pre Change MM#</b>	<b>Pre Change TA</b>	<b>Post Change TA</b>
TLHA0201W	890868	E17592-XXX	E17592-YYY
TLHD0201W	890910	E17593-XXX	E17593-YYY

**PCN Revision History:****Date of Revision:**

June 4, 2008

**Revision Number:**

00

**Reason:**

Originally Published PCN